





DEMI 4100™

Automated Resin Removal Solution

The PostProcess™ DEMI 4100, part of our Submersed Vortex Cavitation (SVC) technology portfolio, enhances post-processing efficiencies for large format resin print technologies. This solution integrates advanced software, hardware, and proprietary chemistry to achieve optimal resin removal, making it a game-changer in high-volume applications.

Increased productivity

Achieve fast processing speeds to deliver significant labor time savings.

• Full software integration

AUTOMAT3D® digital platform allows for full customization, recipe storage and repeatability with one-touch operation.

Enhanced safety

Resin removal chemistry offers an exceedingly safer flashpoint and increased longevity compared to IPA and other solvents.

Software features:

- AUTOMAT3D® intelligent software platform.
- Hands-free cycle times through programmable recipes.
- Propietary Agitation Algorithms.
- Automatic load/unload sequence.

Increased throughput

DEMI 4100 can seamlessly process large part sizes or large builds with many smaller-sized parts, enabling high volume production.

Repeatable results

With a responsive and intuitive AUTOMAT3D® software, DEMI 4100 achieves reliable and consistent results even with complex parts.

Optimal sustainability

Improves sustainability efforts with 10x reduced waste generation compared to IPA.

Hardware features:

- Simple touchscreen interface.
- Large platform and automated lift to handle large format resin printers.

DEMI 4100 Product Specifications

US 240 Volt, 60 Hz, 3-Phase EU 230 Volt, 50 Hz, 3-Phase
35" L x 35" W x 25" H (89 x 89 x 63.5 cm)
200 lbs (90kg)
PLM-403-SUB
265 gallons (998 liters)
Doors Closed: 89" L x 51" W x 89" H (226 x 130 x 227 cm) Doors Open: 155" L x 104" W x 103" H (394 x 264 x 261 cm)
Empty: Approx. 2,730 lbs (1,238 kg) Full: Approx. 5,100 lbs (2,313 kg)
12 months on-site service and support, as per PostProcess Technologies conditions of sale.
Temperature range: 5-40°C (41-104°F) Relative humidity: 0-80%
AUTOMAT3D Windows 10
CE, SGS
Customizable settings with recipe storage capability / Ability to clean parts and trays simultaneously / Up to 10X longevity over IPA / Flashpoint over 200°F / 93°C
Emergency stop / Auto power down / Safety interlocked door
USB Port: USB 3.1 Ethernet: Fully compliant with IEE 802.3, IEEE 802.3u, IEEE 802.3ab
All Vat Photopolymerization resins including rigid, elastomeric, high-temperature and composite filled resins
Designed for all large format printers including those from Stratasys, 3D Systems, Uniontech, and others.

